



COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Product Summary

Device	BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C (Notes 5 & 7)
0.4	00)/	$32m\Omega$ @ $V_{GS} = 10V$	8.1A
Q1	Q1 30V	$46m\Omega @ V_{GS} = 4.5V$	6.1A
00 001/		$39m\Omega$ @ $V_{GS} = -10V$	-7A
Q2	-30V	$53m\Omega$ @ $V_{GS} = -4.5V$	-5.6A

Description

This MOSFET has been designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Power Management Functions
- Analog Switch
- Load Switch

Features

- Low On-Resistance
- N-Channel: 32mΩ @ 10V

46mΩ @ 4.5V

P-Channel: 39mΩ @ -10V

53mΩ @ -4.5V

- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Complementary Pair MOSFET
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

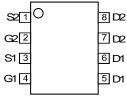
Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Lead Frame. Solderable per MIL-STD-202, Method 208³
- Marking Information (See Page 2)
- Ordering Information
- Weight: 0.072 grams (Approximate)

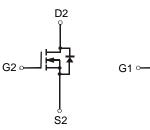




Top View



Top View



N-Channel MOSFET

P-Channel MOSFET

Ordering Information (Note 4)

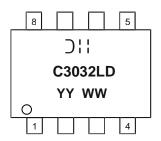
Part Number	Case	Packaging
DMC3032LSD-13	SO-8	2,500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information



O!! = Manufacturer's Marking
C3032LD = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 18 = 2018)
WW = Week (01 to 53)

Maximum Ratings N-CHANNEL – Q1 (@T_A = +25°C, unless otherwise specified.)

Char	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (Note 5)	I _D	8.1 5.1	А
Pulsed Drain Current (Note 6)	I _{DM}	25	Α

Maximum Ratings P-CHANNEL – Q2 (@T_A = +25°C, unless otherwise specified.)

Char	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-30	V
Gate-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (Note 5)	I _D	-7.0 -4.5	А
Pulsed Drain Current (Note 6)	I _{DM}	-25	Α

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Value	Unit
Power Dissipation (Note 5)	P _D	2.5	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	50	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Notes:

- 5. Device mounted on FR-4 PCB, with minimum recommended pad layout.
- 6. Repetitive rating, pulse width limited by junction temperature.

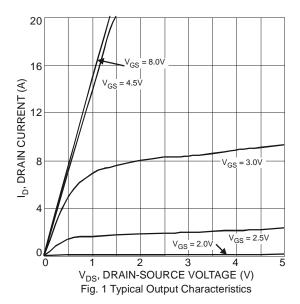


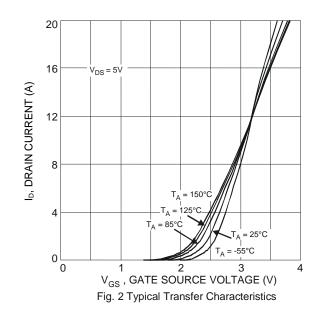
Electrical Characteristics N-CHANNEL - Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	1	μΑ	$V_{DS} = 30V, V_{GS} = 0V$
Gate-Source Leakage	IGSS	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	1	1.45	2.1	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
Static Drain-Source On-Resistance	D		23	32	mΩ	$V_{GS} = 10V, I_D = 7A$
Static Dialit-Source Off-Resistance	R _{DS(ON)}	_	32	46	11152	$V_{GS} = 4.5V, I_D = 5.6A$
Forward Transfer Admittance	Y _{fs}	_	7.6	_	S	$V_{DS} = 5V$, $I_D = 7A$
Diode Forward Voltage (Note 7)	V_{SD}	_	0.7	1	V	$V_{GS} = 0V, I_{S} = 1A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	_	404.5	_	рF	\(\delta = \delta \)
Output Capacitance	Coss	_	51.8	_	рF	V _{DS} = 15V, V _{GS} = 0V, -f = 1MHz
Reverse Transfer Capacitance	C _{rss}	_	45.1	_	pF	
Gate Resistance	Rg	_	1.5	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (10V)	Qg	_	9.2	_	nC	V 40V V 45V
Gate-Source Charge	Q_{gs}	_	1.2	_	nC	$V_{GS} = 10V, V_{DS} = 15V,$ $V_{DS} = 15V,$
Gate-Drain Charge	Q _{gd}	_	1.8	_	nC	ID = 5.6A
Turn-On Delay Time	t _{D(ON)}	_	3.4	_	ns	
Turn-On Rise Time	t _R	_	6.18	_	ns	$V_{GS} = 10V, V_{DS} = 15V,$
Turn-Off Delay Time	t _{D(OFF)}	_	13.92	_	ns	$R_G = 3\Omega$, $R_L = 2.6\Omega$
Turn-Off Fall Time	t _F	_	2.84	_	ns	

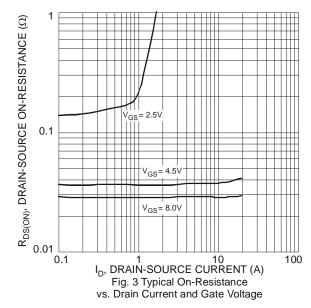
Notes: 7. Short duration pulse test used to minimize self-heating effect.

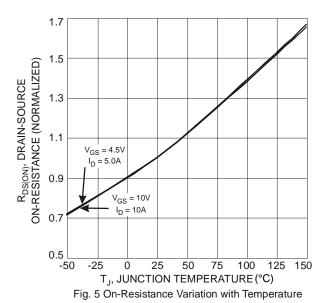
8. Guaranteed by design. Not subject to production testing.

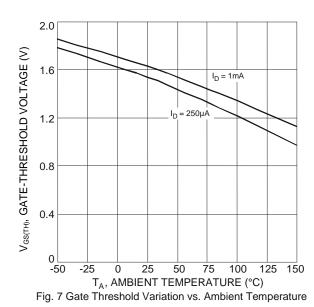












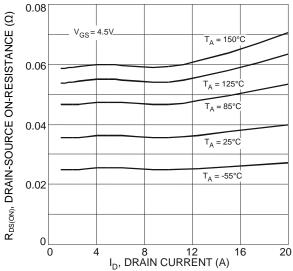


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

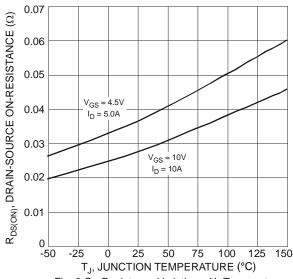


Fig. 6 On-Resistance Variation with Temperature

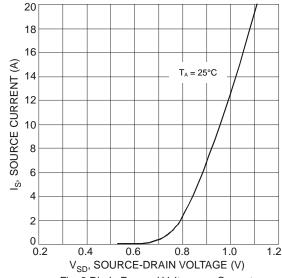
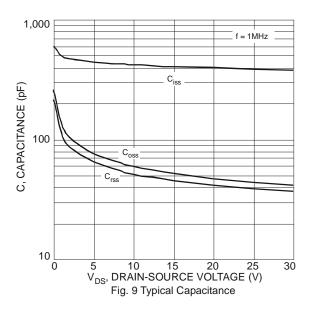
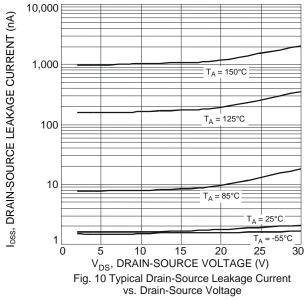


Fig. 8 Diode Forward Voltage vs. Current







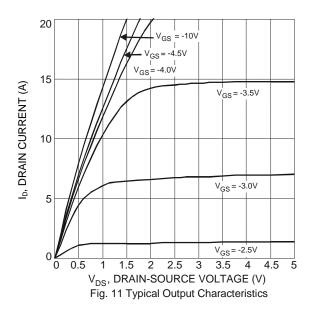


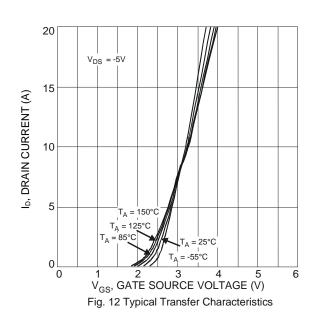
Electrical Characteristics P-CHANNEL (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	-30	_	_	٧	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -30V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	-1	-1.7	-2.2	٧	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
Static Drain-Source On-Resistance	D		30	39	mΩ	$V_{GS} = -10V$, $I_{D} = -4.3A$
Static Dialif-Source Off-Resistance	R _{DS(ON)}	_	42	53	11122	$V_{GS} = -4.5V$, $I_{D} = -3.7A$
Forward Transfer Admittance	Y _{fs}	_	7	_	S	$V_{DS} = -5V, I_{D} = -4.3A$
Diode Forward Voltage (Note 7)	V _{SD}	_	-0.75	-1	V	$V_{GS} = 0V, I_{S} = -1.7A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	_	1002	_	pF	45)/)/
Output Capacitance	Coss	_	125	_	pF	$V_{DS} = -15V, V_{GS} = 0V,$ - f = 1MHz
Reverse Transfer Capacitance	C _{rss}	_	118	_	pF	1 = 1101112
Gate Resistance	Rg	_	13	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (-4.5V)	Qg	_	10.1	_	nC	
Total Gate Charge (-10V)	Qq	_	21.1	_	nC	$V_{GS} = -4.5V/-10V, V_{DS} = -15V,$
Gate-Source Charge	Q _{gs}	_	2.8	_	nC	$I_D = -6A$
Gate-Drain Charge	Q _{qd}	_	3.2	_	nC	
Turn-On Delay Time	t _{D(ON)}	_	10.1	_	ns	
Turn-On Rise Time	t _R	_	6.5	_	ns	$V_{GS} = -10V, V_{DS} = -15V,$
Turn-Off Delay Time	t _{D(OFF)}		50.1	_	ns	$R_G = 6\Omega$, $I_D = -1A$
Turn-Off Fall Time	t _F	_	22.2	_	ns	

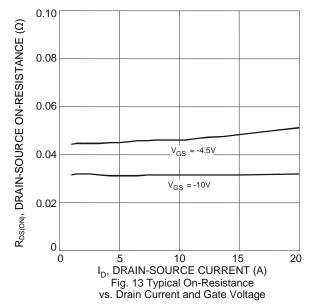
Notes:

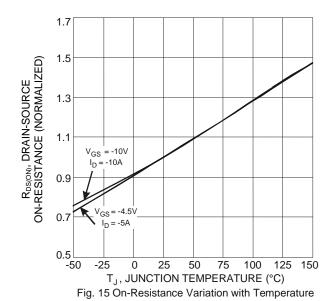
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to production testing.











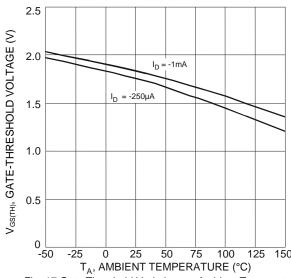


Fig. 17 Gate Threshold Variation vs. Ambient Temperature

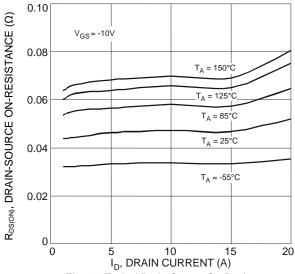


Fig. 14 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

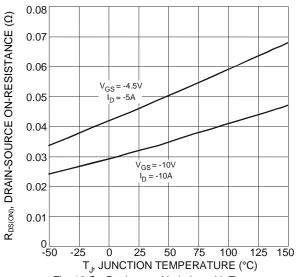


Fig. 16 On-Resistance Variation with Temperature

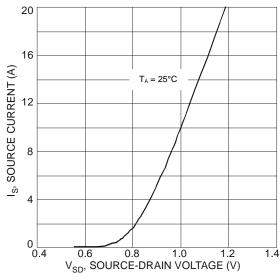
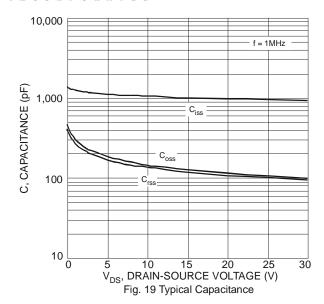
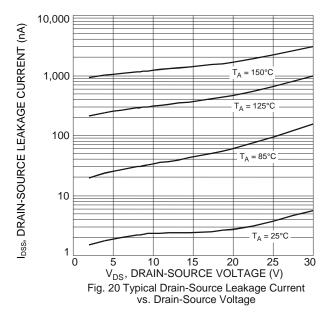


Fig. 18 Diode Forward Voltage vs. Current





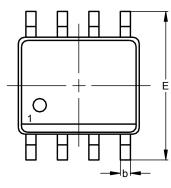


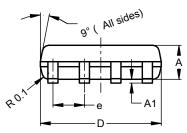


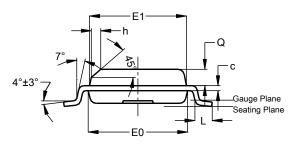
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8





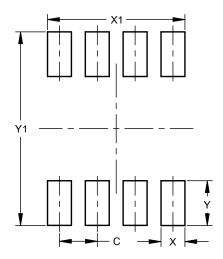


SO-8					
Dim	Min	Max	Тур		
Α	1.40	1.50	1.45		
A1	0.10	0.20	0.15		
b	0.30	0.50	0.40		
С	0.15	0.25	0.20		
D	4.85	4.95	4.90		
Е	5.90	6.10	6.00		
E1	3.80	3.90	3.85		
E0	3.85	3.95	3.90		
е			1.27		
h	-		0.35		
L	0.62	0.82	0.72		
Q	0.60	0.70	0.65		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8



Dimensions	Value (in mm)
С	1.27
Х	0.802
X1	4.612
Y	1.505
V1	6.50



IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2018, Diodes Incorporated

www.diodes.com

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Diodes Incorporated:

DMC3032LSD-13